

MPSOC'18 FORUM REGISTRATION FORM

For registration **before May 31**, the fees are 1400 USD for regular attendees, 1190 USD for IEEE and EDAA members and 850 USD for Speakers. Each speaker is allowed to invite a Junior attendee (student or engineer) with an additional fee of 790 USD. The fee will cover the documentation, the lunch for five days, dinner for four days including the social dinner.

Please mail or fax this form to: MPSOC'18 – MP Associates Inc., 1721 Boulder St. Ste. 107, Louisville, CO 80027 - USA
 Tel: +1 (303) 530-4562 Fax: +1 (303) 530-4334

First Name _____ Last Name _____ Company _____
 Address _____ City _____ State _____ Zip _____
 Country _____ Phone _____ Fax _____ Email _____

Advance registration (before May 31, 2018) – Circle your choice(s)

Regular attendee 1400 USD	IEEE/EDAA member 1190 USD	Student/Junior 790 USD	Speaker 850 USD	2 Days 850 USD
TOTAL FEES _____ USD				

For 2 days only, please circle your choice: **Sun/Mon** **Mon/Tue** **Tue/Wed** **Wed/Thu** **Thu/Fri**

Send full payment in U.S. dollars with this form. Use a check drawn on a US bank or a major credit card. For payments from non-U.S. banks the attendee will be charged a collection fee of US \$30.00. Purchase orders are not accepted. Use your credit card if registering by fax. Make U.S. checks payable to MPSoC.

Form of payment:

Check ___ Credit card ___ Visa ___ Mastercard ___ American Express ___ Card # _____ Exp. date _____
 Name (as it appears on card) _____ Signature _____

Refunds:

Requests for refunds received before May 31, 2018 will be subjected to a \$50 processing fee. No refunds will be made for cancellations received after May 31, 2018 and all registration fees will be forfeited. Register early to avoid disappointment.

MPSoC'18 HOTEL BOOKING



MPSoC'18 will be held in Snowbird, USA From July 29 to August 3 2018

The Cliff Lodge
 9320 South Cliff Lodge Dr
 Snowbird, UT, 84092, USA

Further information is available at: <http://www.mpsoc-forum.org/>



18th International Forum on MPSoC for Software-defined Hardware

July 29 - August 3, 2018, The Lodge at Snowbird, Snowbird, UT, USA

<div style="border: 1px solid black; padding: 2px; font-weight: bold; text-align: center;">FOCUS</div>	<p>Multicore and Multiprocessor SoC (MPSoC) started a new computing era but brought a twofold challenge: building HW easy to use by SW designers and building SW that fully exploits HW capabilities. The main domains addressed at MPSoC are related to adapting HW and SW for better cost, performances and energy efficiency of next generation computing systems. Emerging SW and HW design technologies and architectures combined with advanced semiconductor manufacturing technologies are explored to build energy efficient Manycore and many IP architectures serving advanced computing (image, vision, and cloud) and distributed networked systems.</p>	<p>General Chair: Pierre-Emmanuel Gaillardon, University of Utah, USA</p> <p>Program Co-Chairs: Jishen Zhao, UC Santa Barbara, USA Anca Molnos, CEA-LETI, France Yoshinori Takeuchi, Osaka University, Japan</p> <p>European Liaison Frédéric Petrot, TIMA-INP Grenoble, France Nicolas Ventroux, CEA-LIST, France</p> <p>North American Liaison: Gabriela Nicolescu, Poly. Montreal, Canada</p> <p>Asian Liaison: Sungjoo Yoo, Seoul National University, Korea Shinya Takamaeda-Yamazaki, Hokkaido University, Japan</p> <p>Industry Liaison: Yoshifumi Sakamoto, IBM, Japan Andreas Herkersdorf, TUM, Germany Yuan Xie, UC Santa Barbara, USA</p> <p>Local Organization Chair: Tom Beanel, University of Utah, USA</p> <p>Finance Chair: Ken Stevens, University of Utah, USA Frédéric Rousseau, TIMA-UGA, France</p> <p>Publicity Chair: Fabien Clermidy, CEA-LETI, France Koji Inoué, Kyuchu University, Japan</p> <p>Proceedings Chair: Tom Beanel, University of Utah, USA</p> <p>Web Chair: Edouard Giacomini, University of Utah, USA</p> <p>Technical Program Committee: Marcello Coppola, STMicroelectronics, France Raphaël David, CEA-List, France Rolf Ernst, TU Braunschweig, Germany Giovanni De Micheli, EPFL, Switzerland John Goodacre, ARM, UK Kees Goossens, TUE, The Netherlands Masaharu Imai, Osaka University, Japan Koji Inoue, Kyushu University, Japan Tsuayoshi Isshiki, Tokyo Institute of Tech., Japan Ahmed Jerraya, CEA-Leti, France Rainer Leupers, RWTH Aachen Univ., Germany Youn-long Lin, National Tsing Hua Univ., Taiwan Takashi Miyamori, Toshiba Corp., Japan Gabriela Nicolescu, Poly. Montreal, Canada Frédéric Pétrot, TIMA-INPG, France Pierre Paulin, Synopsys, Canada Kees Vissers, Xilinx, USA Norbert Wehn, Univ. of Kaiserslautern, Germany Marilyn Wolf, Georgia Institute of Tech., USA Hiroto Yasuura, Kyushu University, USA Yoshinori Takeuchi, Osaka University, Japan Hiroyuki Tomiyama, Ritsumeikan Univ., Japan Yuan Xie, UC Santa Barbara, USA Sungjoo Yoo, Seoul National University, Korea</p>
<div style="border: 1px solid black; padding: 2px; font-weight: bold; text-align: center;">CONTENTS</div>	<p>MPSOC is an interdisciplinary forum bringing together key R&D actors from the different fields required to design Multicore and multiprocessor HW and SW systems. The program brings together experts in major HW and SW architectures (Processor, Memory, I/O, Interconnect, RTOS, GFX, Virtualization, application-(domain) specific acceleration & system architectures), design technologies (parallel programming, rapid prototyping, system design models and tools) and emerging semiconductor technologies (heterogeneous integration, 3D, photonics) to build next-generation thinking that will bridge the gap between HW and SW. More than 50 world class R&D speakers will discuss fundamental and strategic issues to master Software-defined Hardware for energy-efficient and high-performance computing.</p> <p>The program includes keynotes on major HW and SW trends and technical sessions to present strategic directions and state-of-the-art research. The 5-day program will also include in-depth technology challenge presentations and short keynotes followed by insightful panels. All the talks will be given by CTO-level speakers from Industry and world-class professors from Academia.</p>	
<div style="border: 1px solid black; padding: 2px; font-weight: bold; text-align: center;">WHY ATTEND</div>	<p>Thanks to its full week format and the high quality of both attendees and speakers, MPSOC is a unique opportunity for executives and senior managers to explore new ideas and refine strategic thinking. MPSOC is the single best event in the world that brings together so many leading thinkers on the future of HW and SW design. It enables great informal networking and interactions with experienced, distinguished researchers and top academic and industrial experts. It builds bridges between different technical areas and corporations/institutes/countries. Finally, it is a unique environment for anyone who wants to share knowledge with researchers and key managers from industry.</p>	
<div style="border: 1px solid black; padding: 2px; font-weight: bold; text-align: center;">FEE</div>	<p>For registration before May 31, the fee amounts to 1400 USD for regular attendees, 1190 USD for IEEE and EDAA members, and 850 USD for speakers. Each speaker is allowed to invite Junior attendee (student) with a fee of 790 USD. It will cover the documentation, the lunch for five days, dinner for four days including the social dinner.</p>	

18th International Forum on MPSoC for Software-defined Hardware

July 29 - August 3, 2018, The Lodge at Snowbird, Snowbird, UT, USA

KEYNOTES

- Rob Aitken, *ARM, UK*
- Shuichi Yamane, *Socionext Inc., Japan*
- Farhang Yazdani, *Broadpak, US*
- Ike Nassi, *TidalScale, US*
- Vance Checketts & Paul Joyce, *Dell EMC, USA*

IN-DEPTH PRESENTATIONS

- Shahar Kvatinsky, *Technion, IL*
- Pei-Lin Pai, *Winbond, TW*
- Yankin Tanurhan, *Synopsys, USA*
- K. Charles Janac, *Arteris Inc., USA*
- Pierre Paulin, *Synopsys, Canada*
- Masatoshi Ishii, *IBM Research - Tokyo, Japan*
- Francois Neumann, *Safran Electronics & Defense, France*

MINI-KEYNOTES

- Pankaj Mehra, *Western Digital Corporation, USA*
- Takashi Miyamori, *Toshiba Corporation, Japan*
- Gabriela Nicolescu, *Ecole Polytechnique de Montréal, Canada*
- Ran Ginosar, *Technion-Israel Institute of Technology, Israël*
- Eric Monchalain, *ATOS, France*
- Song Yao, *DeePhi Tech, China*
- Tsuyoshi Sato, *PIONEER, Japan*
- Kees Vissers, *Xilinx, USA*
- John Goodacre, *ARM, UK*
- Arnaud Grasset, *Thales Research & Tech., France*
- Akihiko Shinya, *NTT Nanophotonics Center, Japan*
- Yuan Xie, *UCSB, USA*
- Yuichi Nakamura, *NEC Corp., Japan*
- Andreas Herkersdorf, *TU Munich, Germany*
- Danilo Pau, *STMicroelectronics, Italy*
- Rolf Ernst, *Technische Universitat Braunschweig, Germany*

MINI-KEYNOTES

- Kees van Berkel, *Ericsson, Eindhoven University of Technology, The Netherlands*
- Jishen Zhao, *UCSC, USA*
- Marilyn Wolf, *Georgia Tech, USA*
- Yoshifumi Sakamoto, *IBM Japan, Japan*
- Norbert Wehn, *University of Kaiserslautern, Germany*
- Fumio Arakawa, *Nagoya University, Japan*
- Frédéric Pétrot, *TIMA Lab, Grenoble University, France*
- Frederic Rousseau, *TIMA Lab, Grenoble University, France*
- Anca Molnos, *CEA-Leti, France*
- Jiang Xu, *Hong Kong University of Science and Technology, Hong Kong*
- Koji Inoue, *Kyushu University, Japan*
- Tsuyoshi Isshiki, *Tokyo Institute of Technology, Japan*
- Masaaki Kondo, *The University of Tokyo, Japan*
- Yoshinori Takeuchi, *Osaka University, Japan*
- Tohru Ishihara, *Kyoto University, Japan*
- Sungjoo Yoo, *Seoul National University, Korea*
- Youn-Long Lin, *National Tsing Hua University, Taiwan*
- Weihua Sheng, *Silexica, Germany*
- Yuko Hara-Azumi, *Tokyo Institute of Technology, Japan*
- Hiroki Matsutani, *Keio University, Japan*
- Nicolas Ventroux, *CEA-List, France*
- Rainer Leupers, *RWTH Aachen University, Germany*
- Ittetsu Taniguchi, *Graduate School of Information Science and Technology Osaka University, Japan*
- Wei Zhang, *Hong Kong University of Science and Technology, Hong Kong*
- Masaki Gondo, *eSOL Co.,Ltd., Japan*
- Koichiro Yamashita, *Fujitsu Laboratories LTD., Japan*
- Victor Grimblatt, *Synopsys Chile R&D Center, Latin America*
- Shinya Takamaeda, *Hokkaido University, Japan*

Total speakers: 57